



- SPECIFICATIONS:**
- ELECTRICAL CHARACTERISTICS:**
 - 1-1. RATING: 12V 1A
 - 1-2. CONTACT RESISTANCE: 30m MAX (PERFORM Ω)
 - 1-3. DIELECTRIC VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE
 - 1-4. INSULATION RESISTANCE: 100M MIN. MEASURED BY 500 VDC
 - MECHANICAL CHARACTERISTICS:**
 - 2-1. INSERTED FORCE : 3.0 KGF MAX.
 - 2-2. WITHDRAWAL FORCE : 0.3-3.0 KGF
 - LIFE TEST:** 5,000 CYCLES MIN.
 - TO CONFORM TO THE SINGATON HSF SPECIFICATION**
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK:**
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:**
 - FOR REFLOW SOLDERING LEAD-FREE PROCESS.**
 - PACKAGING: TAPE & REEL.**

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
A	BODY	1	HI-TEMP THERMOPLASTIC	BLACK
B	SHUNT A	1	COPPER ALLOY 0.2t	GOLD FLASH
C	TIP	1	COPPER ALLOY 0.2t	GOLD FLASH
D	RING-B	1	COPPER ALLOY 0.2t	GOLD FLASH
E	RING-A	1	COPPER ALLOY 0.2t	GOLD FLASH
F	SHUNT B	1	COPPER ALLOY 0.2t	GOLD FLASH
G	EARTH	1	COPPER ALLOY 0.2t	GOLD FLASH

DECIMALS:	ANGLES:	TITLE
X : ±0.5	X : ±2°	.3.5 PHONE JACK
X.X : ±0.3	X.X : ±1°	PART NO. 2SJ2321-005111F
X.XX : ±0.2		SCALE 1:1 (UNIT: mm)
		SIZE: A3 SHEET: 10*7
		REV: A

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	Sticky	2011.08.17

Singaton Enterprise Co., Ltd.
信音企業股份有限公司

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